ACF Flip Chip Mounter

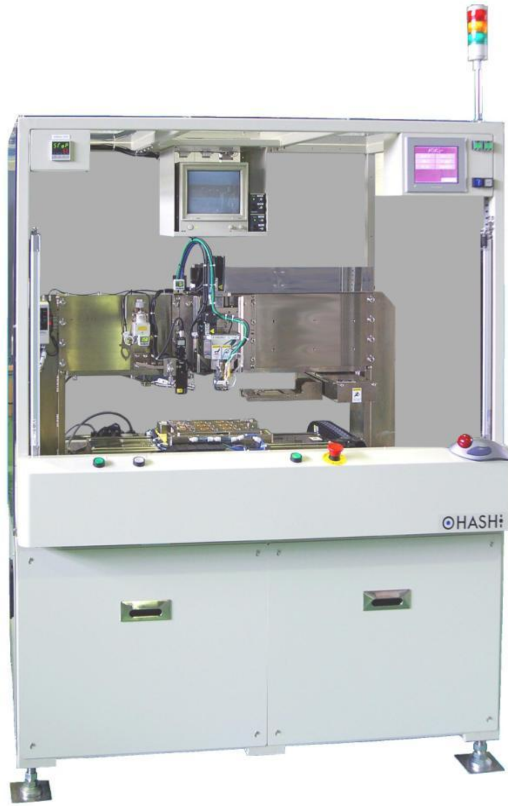
MS-02

Previous Model #
CAM-120

ACF Equipment Partner

OHASHI

OHASHI Engineering. Co., Ltd.



Process

IC Flip Chip Mounting

ACF Flip Chip Mounter with Automatic Alignment System

Equipment Overview

The MS-02 is a semi-automatic Flip Chip Mounted with auto-matic alignment. The substrate is placed with the unit and multiple chips can be mounted in an array either on the same or across multiple substrates.

Equipment dimension W x D x H

1200 x 1100 x 2000 (mm)

Weight About 1000 Kg

Number of operators

1 person

Productivity

7.5 sec per chip
Excludes loading & unloading
For reference only.

COG and COF

The MS-02 supports both COG (Chip-on-Glass) and COF (Chip-on-Flex) applications with minimal changeover.

COF Carrier Bonding (Option)

COF carrier support (250(W) x 400(D)) greatly increases throughput and repeatability.

Ideal for Mid-Size COG Projects

A large bonding stage allows this unit to support COG applications with up to 12 inch panels.

Common Carrier System

Units in this line, inlcuding the MS-02, use a common carrier to improve throughput and reduce cost.

Spec. overview

Stage size	(W)250 x (D)400mm
Tool size	Max. (W)20 x (D)20mm
Utilities	Compressed air 0.49Mpa Vacuum source installed 200-220V Single phase 4KVA
Bonding quantity	X=9pcs. Y=9pcs.
Bonding accuracy	±3um(COG) 4um(COF)
Waffle Pack	2, 3, & 4-inch, face down

Manufacturer

OHASHI Engineering. Co., Ltd.
1-471-8, Toyonodai, Otone、Kita-Saitama, Saitama
TEL +81-480-72-7500 FAX +81-480-72-7415
http//www.ohashi-engineering.co.jp

Distributor

www.ito-group.com

2010/1/29